

In the Claims

Please cancel claims 67-69.

Please amend claims 52-62 and add claims 70-76.

A clean version of the amended and added claims follows. In addition, a marked version of the amended claims showing the changes follows the Remarks section.

Clean Version Of Amended And Added Claims

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52. (amended) A semiconductor component comprising:
a substrate comprising a plurality of tested semiconductor components including a plurality of good components and at least one defective component; and
a plurality of conductors on the substrate configured to provide electrical paths to the good components while electrically isolating the at least one defective component.

53. (amended) The component of claim 52 wherein the substrate comprises a semiconductor wafer and the components comprise semiconductor dice or semiconductor packages.

sub 52

54. (amended) The component of claim 52 wherein the conductors comprise a laser patterned redistribution layer.

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55. (amended) The component of claim 52 wherein the conductors are configured to electrically connect multiple components in a cluster that excludes the at least one defective component.

56. (amended) A semiconductor component comprising:
a substrate comprising a plurality of tested components, each component comprising a plurality of component contacts;

the components including a plurality of good components and a defective component; and

a plurality of laser patterned conductors on the substrate configured to provide electrical paths between the component contacts on the good components and to electrically isolate, the component contacts on the defective component.

57. (amended) The component of claim 56 wherein the conductors comprise a metal redistribution layer.

58. (amended) The component of claim 56 wherein the conductors are configured to electrically connect a plurality of good components in a cluster.

59. (amended) The component of claim 56 wherein the substrate comprises a semiconductor wafer, and the components comprise semiconductor dice or semiconductor packages.

60. (amended) A semiconductor component comprising:
a semiconductor die comprising a plurality of integrated circuits and a plurality of component contacts in electrical communication with the integrated circuits;

a plurality of conductors on the die in electrical communication with the component contacts; and

a plurality of terminal contacts on the die in electrical communication with the conductors;

at least some of the conductors configured to interconnect or electrically isolate selected component

contacts or selected terminal contacts to repair defects on the die.

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61. (amended) The component of claim 60 wherein the terminal contacts comprise a ball grid array.

62. (amended) The component of claim 60 wherein the conductors comprise a laser patterned redistribution layer.

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70. (added) A semiconductor component comprising:
a semiconductor die comprising a plurality of integrated circuits including at least one defective integrated circuit;
a plurality of terminal contacts on the die; and
a redistribution layer on the die comprising a plurality of laser patterned conductors configured to electrically connect the terminal contacts to the integrated circuits and to electrically isolate the terminal contacts from the at least one defective integrated circuits.

71. (added) The component of claim 60 wherein the terminal contacts comprise balls or bumps in a grid array.

72. (added) The component of claim 60 further comprising a plurality of bond pads on the die in electrical communication with the integrated circuits and the conductors.

73. (added) The component of claim 60 wherein the redistribution layer comprises a metal.

74. (added) The component of claim 60 wherein the conductors are separated by etched openings.

75. (added) The component of claim 60 further comprising a protective layer on the conductors having a plurality of openings for the terminal contacts.

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~~75.~~ (added) The component of claim 60 wherein the conductors comprise a deposited metal.

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~~76.~~ (added) The component of claim 60 wherein the conductors are configured to repair the at least one defective integrated circuits.
